

Title (en)  
SUBSTRATE AND METHOD FOR CULTURE OF FUNGI, INCLUDING SHIITAKE (LENTINUS EDODES).

Title (de)  
SUBSTRAT UND ZUCHTVERFAHREN FÜR PILZE EINSCHLIESSLICH SHIITAKE (LENTINUS EDODES).

Title (fr)  
SUBSTRAT ET PROCEDE DE CULTURE DE CHAMPIGNONS, DONT LE SHIITAKE (LENTINUS EDODES).

Publication  
**EP 0504142 A1 19920923 (EN)**

Application  
**EP 90911078 A 19900626**

Priority  
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Abstract (en)  
[origin: WO9100002A1] An improved substrate and method for culturing fungi, including Shiitake. The substrate is essentially cellulose-free and comprises a major portion of grain and minor portions of nutritional supplements. The grain is partially sterilized by boiling in order to kill bacteria, cooled in order to induce germination of the heat resistant spores, and steam sterilized before the germinated spores have matured sufficiently to create new spores. The substrate is inoculated with fungi, which are then cultured.

Abstract (fr)  
Substrat amélioré et procédé de culture de champignons, dont le Shiitake. Le substrat est essentiellement dépourvu de cellulose et comporte une portion importante de céréales et de petites portions de suppléments nutritionnels. Les céréales sont en partie stérilisées par ébullition afin de tuer des bactéries, refroidies afin de provoquer la germination des spores résistantes à la chaleur, et stérilisées à la vapeur avant que les spores germinées n'aient suffisamment mûri pour pouvoir créer de nouvelles spores. Le substrat est inoculé avec des champignons, qui sont ensuite cultivés.

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